

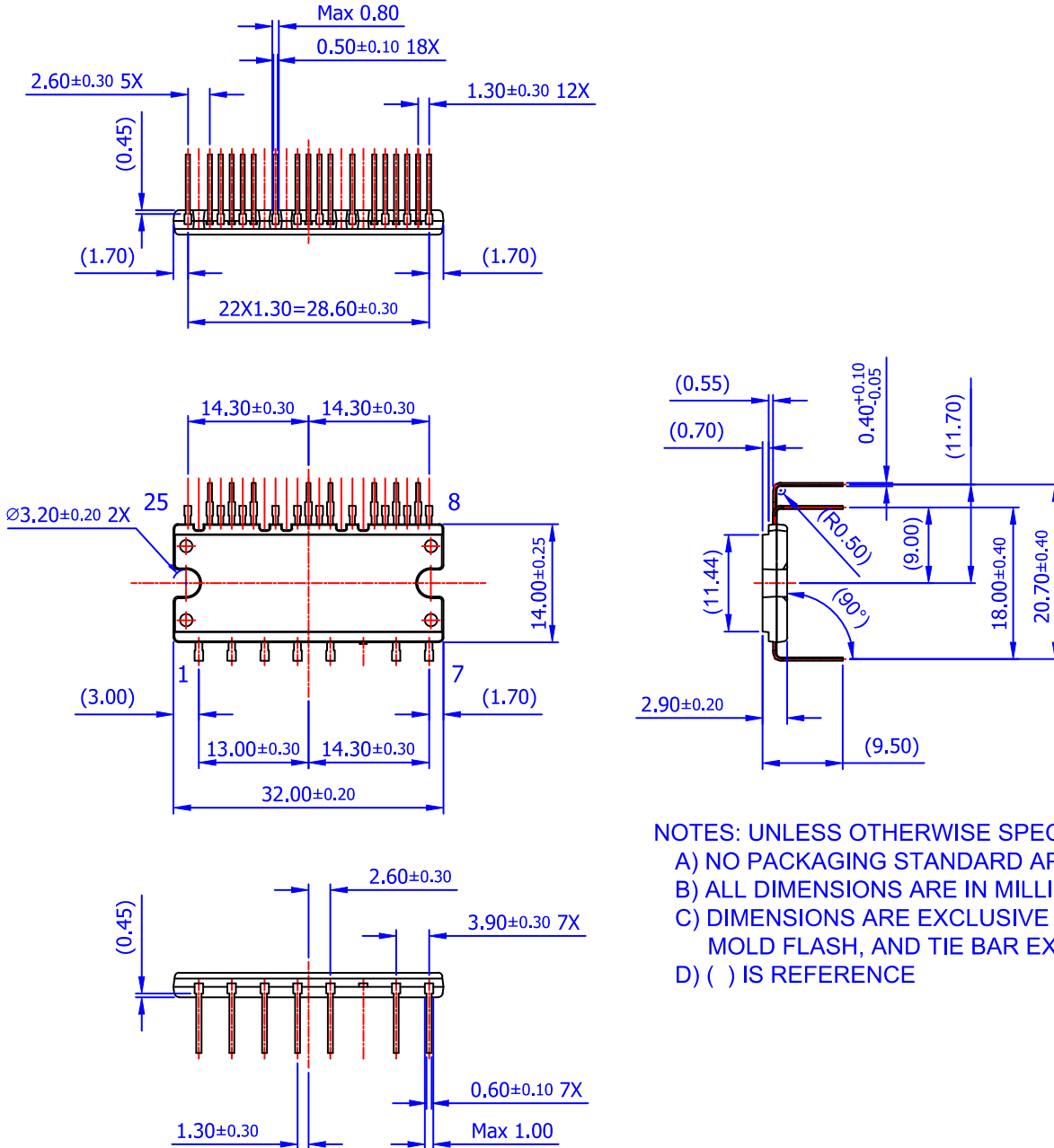
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®



SPMFA-A25 / 25LD, FULL PACK, DIP TYPE, SPM8 SERIES
CASE MODE Z
ISSUE O

DATE 31 JAN 2017



NOTES: UNLESS OTHERWISE SPECIFIED
 A) NO PACKAGING STANDARD APPLIES
 B) ALL DIMENSIONS ARE IN MILLIMETERS
 C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
 D) () IS REFERENCE

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	SPMFA-A25 / 25LD, FULL PACK, DIP TYPE, SPM8 SERIES	PAGE 1 OF 2

